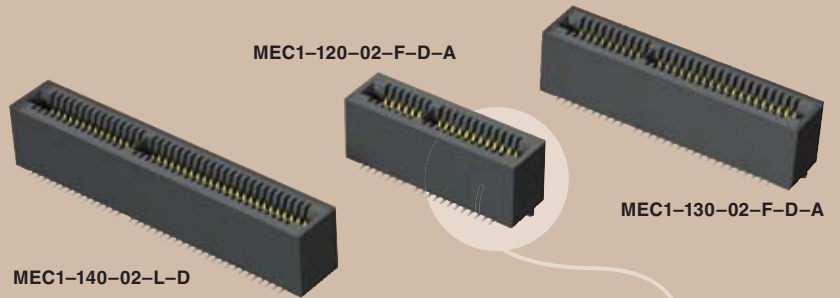


(1,00mm) .03937"

MEC1 SERIES



MINI EDGE CARD SOCKET

SPECIFICATIONS

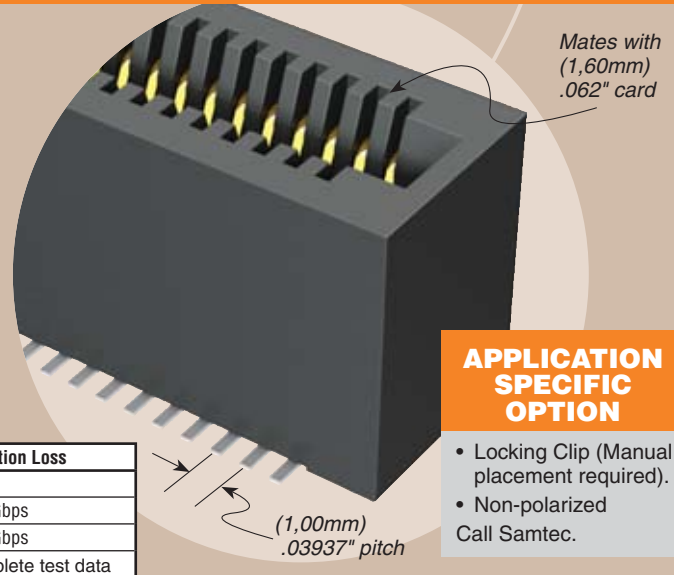
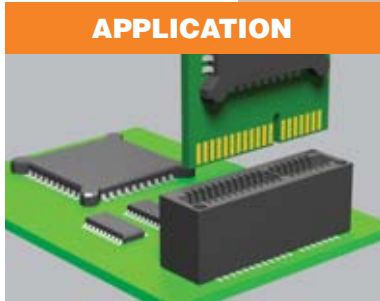
For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

- Insulator Material:** Black LCP
- Contact Material:** BeCu
- Plating:** Sn or Au over 50µ" (1,27µm) Ni
- Operating Temp Range:** -55°C to +125°C
- Current Rating:** 2A @ 80°C ambient (See website for details)
- Voltage Rating:** 300 VAC
- Insertion Depth:** (5,84mm) .230" to (8,13mm) .320"
- RoHS Compliant:** Yes



- Processing:** Lead-Free Solderable: Yes
- SMT Lead Coplanarity:** (0,10mm) .004" max (05-20) (0,15mm) .006" max (30-70)

Mates with:
(1,60mm) .062" card



- ### APPLICATION SPECIFIC OPTION
- Locking Clip (Manual placement required).
 - Non-polarized Call Samtec.

1mm MEC1	Rated @ 3dB Insertion Loss
9,19mm Stack Height	
Single-Ended Signaling	5.5 GHz / 11 Gbps
Differential Pair Signaling	6.5 GHz / 13 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?MEC1 or contact sig@samtec.com

MEC1 - **1** POSITIONS PER ROW - **02** - **PLATING OPTION** - **D** - **OTHER OPTION**

05, 08, 20, 30, 40, 50, 60, 70

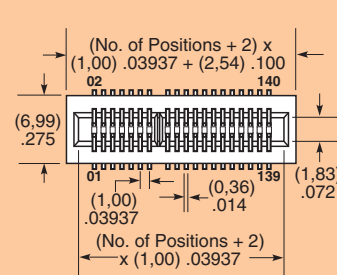
-F
= Gold flash on contact, Matte tin on tail

-L
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

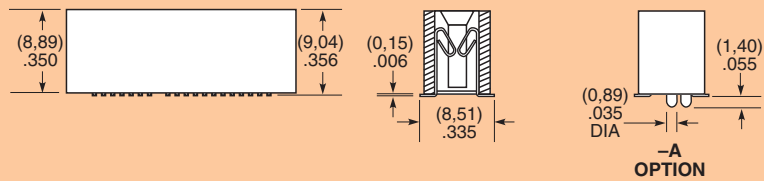
-A
= Alignment Pin metal or plastic at Samtec discretion.

-K
= (7,87mm) .310" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116



Important Note: Samtec recommends that pads on the mating board be Gold plated.

Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM